



3rd Asia Symposium on Quality Electronic Design (ASQED) Announces Program; Convenes July 19-20, Kuala Lumpur, Malaysia

SAN JOSE, CA and Kuala Lumpur, Malaysia – May 18, 2011 – The third **Asia Symposium on Quality Electronic Design (ASQED)** today announced its 2011 [program](#) consisting of several keynotes by industry leaders and university experts, tutorials and over 50 technical presentations

[ASQED](#) is being held on July 19-20, 2011 in Kuala Lumpur, Malaysia. ASQED plays a critical role in promoting quality-based electronic design and manufacturing in Asia and plans to be an integral part of establishing a communication link between semiconductor, nano-electronic, bio-electronic, MEMS (microelectromechanical) and NEMS (nanoelectromechanical) systems, and photovoltaic (PV) technologies and disciplines such as design, manufacturing, test and packaging.

Powerful Keynotes Headline Conference

[ASQED](#) keynote sessions are sponsored by Synopsys and include:

[Nanotechnology and the Challenges Facing Designers of Circuits and Systems](#)

Prof. Arokia Nathan

***Chair of Nanotechnology, London Centre for Nanotechnology,
University College London, England***

[Electronics for Energy Management](#)

Dr. Bernard Courtois

Director of CMP and TIMA, France

[The Packaging Technology Domain](#)

Prof. Younggap You

Dean of College of Electrical and Computer Engineering, Chungbuk National University, Korea

[Challenges in Interconnection](#)

Dr. ChoonHeung Lee

Head of Corp. Technology, Amkor, Korea

[Advances in High Density Interconnections-Promoting Innovations and Lower Costs](#)

Happy Holden

Chief Technical Officer, Foxconn Advanced Technology, Taiwan

Tutorials

[ASQED](#) is pleased to offer the following tutorials by industry experts:

A Tool Box for Successful 3D Integration

Mark Scannell

Program Director, 3D Integration

CEA – Léti, France

Modern 3D Packaging Technologies Driving the Need for IC, Package and Printed Circuit Board (PCB) Co-Design Methodologies

John Park

Methodology Architect

Mentor Graphics, USA

Memory Packaging Challenges and Approaches for the Evolving World of the Portable Client and Cloud

Richard Crisp

Principal Technologist

Tessera, USA

3D Silicon Interposer and Through Silicon Via (TSV): Application, Requirement, Infrastructure and Technologies

Farhang Yazdani

President and CTO

BroadPak Corporation, USA

Technical Sessions

The [ASQED technical sessions](#) consist of over 50 papers by engineers and researchers worldwide.

About ISQED

[ASQED](#) is the third event organized by the International Society for Quality Electronic Design (www.ISQED.com) in Asia. Conference proceedings are published by the IEEE.

Please visit <http://www.asqed.com> for more information and to register.

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